
EMBER[®] EM3X MODULE TECHNICAL SPECIFICATION

Silicon Labs' EM3x development kits contain various modules designed around the EM3x family of ICs. All of these modules are designed and sold by Silicon Labs' module partners Telegesis (UK) Limited and California Eastern Laboratories (CEL). The module designs allow them to be integrated into any product without the need for RF experience and expertise. Utilizing stacks such as Silicon Labs' certified ZigBee network stack EmberZNet, these modules enable a developer to add powerful wireless networking capability to products and quickly bring them to market.

This document provides the technical specification of the EM3x modules on its Silicon Labs-specific carrier board. For more information on the other Telegesis modules, contact Telegesis, Ltd directly at www.telegesis.com. For more information on other CEL modules, contact CEL directly at meshconnect.cel.com.

New in This Revision

Added CEL CE compliance information.

Contents

| | | |
|-----|---------------------------------------|---|
| 1 | EM3x Module Definitions..... | 2 |
| 2 | EM3x Module Features | 3 |
| 3 | Performance Characteristics | 3 |
| 4 | EM3x Configurations..... | 5 |
| 5 | Mechanical Details..... | 7 |
| 5.1 | EM3x Module Interface Connector | 8 |

1 EM3x Module Definitions

To accommodate the requirements of the different markets, Telegesis and CEL have developed a series of pin-compatible modules based on the Ember EM341, EM346, EM357, and EM3588 chipsets. Table 1 defines the Telegesis, CEL, and Silicon Labs part numbers for each module as well as describes the differences (Power Amplifier (PA), Low Noise Amplifier (LNA), and RF connection) between each module.

Table 1. Silicon Labs and Module Partner Part Numbers

| Silicon Labs P/N | Silicon Labs Orderable Part Number (OPN) | EM3x IC | Module Partner | Module Partner P/N (Module only) | RF Connection | PA / LNA? (Long Range) |
|------------------|--|---------|----------------|----------------------------------|-------------------|------------------------|
| 110-0740-000 | EM341-MOD-ANT-C | EM341 | CEL | ZICM341SP0-1 | Antenna | No |
| 110-0741-000 | EM341-MOD-RF-C | EM341 | CEL | ZICM341SP0-1C | Connector | No |
| 110-0742-000 | EM346-MOD-ANT-C | EM346 | CEL | ZICM346SP0-1 | Antenna | No |
| 110-0743-000 | EM346-MOD-RF-C | EM346 | CEL | ZICM346SP0-1C | Connector | No |
| 110-0720-000 | EM357-MOD-ANT-T | EM357 | Telegesis | ETRX357 | SMT Antenna | No |
| 110-0721-000 | EM357-MOD-RF-T | EM357 | Telegesis | ETRX357HR | Mini-RF Connector | No |
| 110-0722-000 | EM357-MOD-LR-RF-T | EM357 | Telegesis | ETRX357HR-LRS | Mini-RF Connector | Yes |
| 110-0723-000 | EM357-MOD-LR-ANT-T | EM357 | Telegesis | ETRX357-LRS | SMT Antenna | Yes |
| 110-0730-000 | EM357-MOD-ANT-C | EM357 | CEL | ZICM357SP0-1 | SMT Antenna | No |
| 110-0731-000 | EM357-MOD-RF-C | EM357 | CEL | ZICM357SP0-1C | Mini-RF Connector | No |
| 110-0732-000 | EM357-MOD-LR-RF-C | EM357 | CEL | ZICM357SP2-1C | Mini-RF Connector | Yes |
| 110-0733-000 | EM357-MOD-LR-ANT-C | EM357 | CEL | ZICM357SP2-1 | SMT Antenna | Yes |
| 110-0734-000 | EM3588-M-AN-C | EM3588 | CEL | ZICM3588SP0-1 | SMT Antenna | No |
| 110-0735-000 | EM3588-MOD-RF-C | EM3588 | CEL | ZICM3588SP0-1C | Mini-RF Connector | No |
| 110-0736-000 | EM3588-MLR-RF-C | EM3588 | CEL | ZICM3588SP2-1C | Mini-RF Connector | Yes |
| 110-0737-000 | EM3588-MLR-AN-C | EM3588 | CEL | ZICM3588SP2-1 | SMT Antenna | Yes |

All of these modules are available from Telegesis and CEL. Silicon Labs provides the CEL EM357 and EM3588 module types with the EM35x Development Kit (part number EM35X-DEV) and the EM341 and EM346 modules with the EM34x Development Kit (part number EM34X-DEV).

For modules whose RF connection is a mini-RF connector, an RF adapter cable (Tyco/Amp part number 2032440-1) can be used to interface the module to external test equipment. One of these RF adapter cables is included with the development kits.

To connect to the EM35x breakout board (Silicon Labs P/N: 130-0680-000), each module shown in Table 1 is soldered to a small carrier board. The carrier board connector is discussed in section 5.1, EM3x Module Interface Connector.

2 EM3x Module Features

Module features:

- Small form factor, SMT module (25 mm x 19 mm)
- Side castellation for easy soldering and inspection
- Industry standard JTAG Programming and real-time network level debugging via the Packet Trace Port.
- Wide supply voltage range (2.1 to 3.6 V)
- Low sleep current (< 1 μ A for EM35x and EM34x, < 2 μ A for EM3588)
- Access to all EM3x GPIO from the System-on-Chip (SoC)
- Access to either a U.FL RF Connector or a SMT antenna allows flexibility in antenna selection process
- FCC compliance

Telegesis:

FCC ID: S4GEM35XA

CEL:

FCC ID: W7Z-ZICM357SPO

FCC ID: W7Z-ZICM357SP2

- CE compliance

Telegesis:

Radio: EN300 328 v1.7.1

EMC: EN301 489-17 v2.1.1

Safety: EN60950-1

CEL

Radio: EN 300 328 V1.8.1 (2006 - 2012)

EMC: EN 301 489-1 V1.8.1, V1.9.1

EN 301 489-17 V2.2.1

- Long Range versions with a link budget of up to 124 dB

Module with carrier board features:

- Access to the Packet Trace Port connector (allows for direct connection to the Ember Debug Adapter (ISA3) for programming and debugging)
- Two debug LEDs
- Access to all EM3x GPIO through a robust 0.05" pitch connector

3 Performance Characteristics

This section describes the characteristics of the module with carrier board. For more information on the EM35x and EM34x SoC performance, refer to the EM35x, EM358x, EM341 and EM346 data sheets.

Unless specified, the data within each of the tables was gathered at room temperature (25 °C) and 3.0 V source potential. Table 2 summarizes the recommended operating conditions for the modules.

Table 2. Recommended Operating Conditions for the EM3x Module

| Parameter | Min | Typ | Max | Unit |
|-----------------------------|------|-----|------|------|
| VDD supply | 2.1 | — | 3.6 | V |
| RF Input Frequency | 2405 | — | 2480 | MHz |
| RF Input Power (at RF Port) | — | — | 0 | dBm |
| Operating Temperature Range | -40 | — | 85 | °C |

Table 3 summarizes the DC characteristics at 25 °C and VDD of 3 V of the EM3x Module.

Table 3. DC Characteristics of the EM3x Module

| Parameter | Min | Typ | Max | Unit |
|-------------------------------|-----|------|-----|------|
| VDD supply | 2.1 | — | 3.6 | V |
| Sleep Current (RC oscillator) | — | 0.4 | — | μA |
| Active Current (TX) | | | | |
| TX, Normal Mode, +3 dBm | — | 31 | — | mA |
| TX, Boost Mode, +8 dBm | — | 39 | — | mA |
| TX, Normal Mode, 0 dBm | — | 28.5 | — | |
| Active Current (RX) | | | | |
| RX, Normal Mode | — | 26 | — | mA |
| RX, Boost Mode | — | 27 | — | mA |
| Wake Time from Deep Sleep | — | 100 | — | us |
| Shutdown Time | — | 5 | — | us |

Table 4 summarizes the digital I/Os at VCC = 3 V and 25 °C of the EM3x Module.

Table 4. Digital I/O Characteristics of the EM3x Module

| Parameter | Min | Typ | Max | Unit |
|---------------------------------|------------|-----|------------|------|
| Input Logic Threshold | | | | |
| Schmitt threshold (high to low) | 0.42 x VDD | — | 0.5 x VDD | V |
| Schmitt threshold (low to high) | 0.62 x VDD | — | 0.8 x VDD | V |
| Input Current | | | | |
| Logic Low | — | — | -0.5 | μA |
| Logic High | — | — | 0.5 | μA |
| Output Voltage | | | | |
| Logic Low | 0 | — | 0.18 x VDD | V |
| Logic High | 0.82 x VDD | — | VDD | V |
| Output Current | | | | |
| Source, Standard Pad | — | — | 4 | mA |
| Sink, Standard Pad | — | — | 4 | mA |
| Source, High Current Pad | — | — | 8 | mA |
| Sink, High Current Pad | — | — | 8 | mA |
| Total Output Current | — | — | 40 | mA |

Table 5 summarizes the RF parameters of the EM3x Module.

Table 5. RF Characteristics of the EM3x Module

| Parameter | Min | Typ | Max | Unit |
|--|------|------|------|------|
| Frequency Range | 2405 | — | 2480 | MHz |
| Channel Spacing | — | 5 | — | MHz |
| RX Sensitivity (1% PER, 20-byte packet) | | | | |
| Normal Mode | — | -100 | -94 | dBm |
| Boost Mode | — | -101 | -95 | dBm |
| Adjacent Channel Rejection | | | | |
| High Side | — | 35 | — | dB |
| Low Side | — | 35 | — | dB |
| 2 nd High Side | — | 43 | — | dB |
| 2 nd Low Side | — | 43 | — | dB |
| All other channels | — | 40 | — | dB |
| TX Power (Maximum) | | | | |
| Boost Mode | — | 8 | — | dBm |
| Normal Mode | — | 3 | — | dBm |
| Error Vector Magnitude (Offset EVM) (per IEEE 802.15.4-2003) | — | 5 | 15 | % |
| PSD (3.5 MHz from carrier) | | | | |
| Relative | -20 | — | — | dB |
| Absolute | -30 | — | — | dBm |

4 EM3x Configurations

The IC on the EM3x Module can be set to different RF frequency channels as well as different power levels. When using the nodetest application on the module, the frequency channels and output power levels can be configured through a command line interface (CLI).

In order to configure the output power, the setTXPower command can be used. Table 6 demonstrates the setTXPower command and the expected power output. Note that these are the typical expected power output levels based on the performance of the EM3x IC and actual results are dependent on the module provider design implementation.

Note: Table 6 refers to the non-PA versions of the modules. For the version with a PA, the output power should be set to -5 dBm in order to achieve +20 dBm output power.

Table 6: List of TX output powers when using SetTxPower

| SetTxPower [signed hexadecimal] | Output Power (dBm) |
|------------------------------------|-----------------------|
| SetTxPower 9 | +3 |
| SetTxPower 8 | +8 |
| SetTxPower 7 | +7 |
| SetTxPower 6 | +6 |
| SetTxPower 5 | +5 |

| SetTxPower [signed hexadecimal] | Output Power (dBm) |
|--|-------------------------------|
| SetTxPower 4 | +4 |
| SetTxPower 3 | +3 |
| SetTxPower 2 | +2 |
| SetTxPower 1 | +1 |
| SetTxPower 0 | 0 |
| SetTxPower -1 | -1 |
| SetTxPower -2 | -2 |
| SetTxPower -3 | -3 |
| SetTxPower -4 | -4 |
| SetTxPower -5 | -5 |
| SetTxPower -6 | -6 |
| SetTxPower -7 | -7 |
| SetTxPower -8 | -8 |
| SetTxPower -9 | -9 |
| SetTxPower -a | -9 |
| SetTxPower -b | -11 |
| SetTxPower -c | -12 |
| SetTxPower -d | -12 |
| SetTxPower -e | -14 |
| SetTxPower -f | -14 |
| SetTxPower -10 | -14 |
| SetTxPower -11 | -17 |
| SetTxPower -12 | -17 |
| SetTxPower -13 | -17 |
| SetTxPower -14 | -20 |
| SetTxPower -15 | -20 |
| SetTxPower -16 | -20 |
| SetTxPower -17 | -20 |

To change the channel, the setChannel command can be used (assuming nodetest application is on the device). Table 7 lists the valid parameters to be used with setChannel command.

Table 7: List of setChannel values for EM3x

| setChannel (decimal) | Center Frequency (GHz) | radioChannel (decimal) | Center Frequency (GHz) |
|----------------------|------------------------|------------------------|------------------------|
| 11 | 2.405 | 19 | 2.445 |
| 12 | 2.410 | 20 | 2.450 |
| 13 | 2.415 | 21 | 2.455 |
| 14 | 2.420 | 22 | 2.460 |
| 15 | 2.425 | 23 | 2.465 |
| 16 | 2.430 | 24 | 2.470 |
| 17 | 2.435 | 25 | 2.475 |
| 18 | 2.440 | 26 | 2.480 |

5 Mechanical Details

Figure 1 illustrates the ZICM35x Module carrier board from CEL, while Figure 2 illustrates the ETRX35x Module from Telegesis on a carrier board.

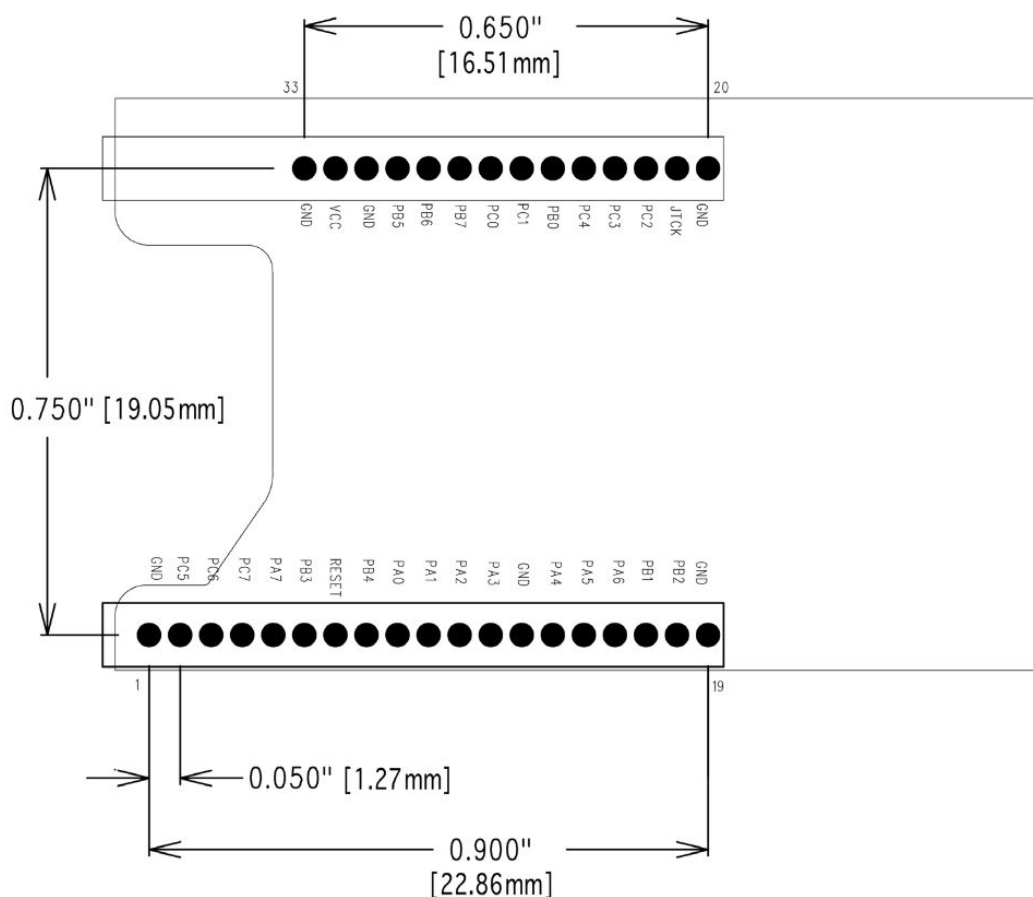


Figure 1. CEL ZICM35x Module Carrier Board

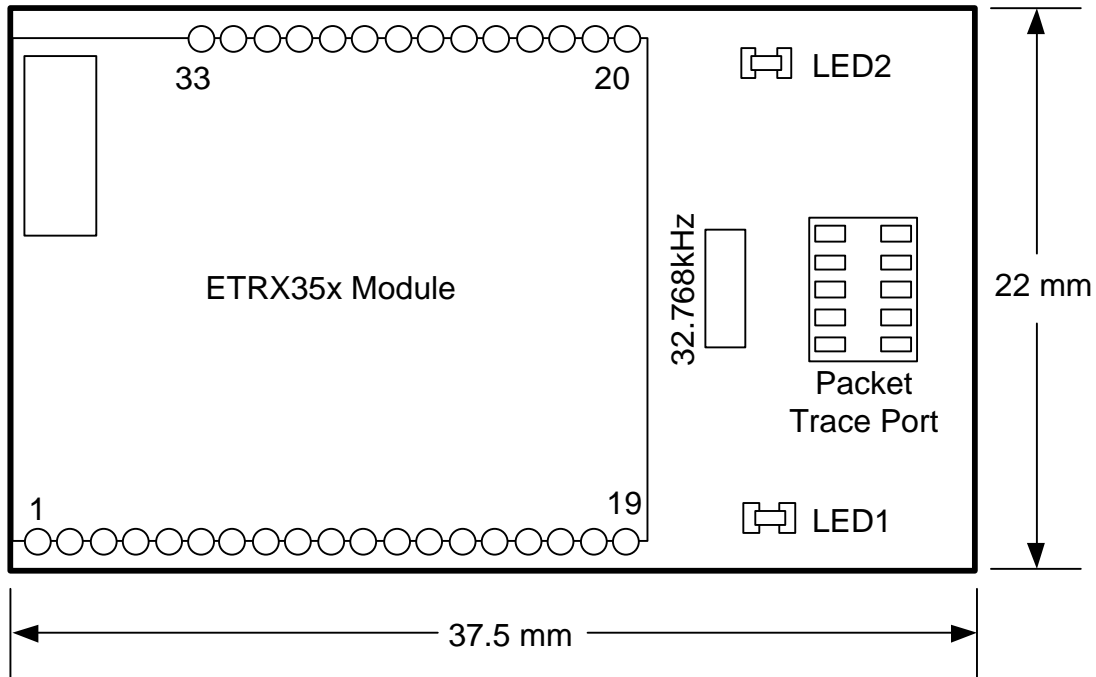


Figure 2. Telegesis ETRX35x Module with Carrier Board

5.1 EM3x Module Interface Connector

Two single-row, 0.05” pitch, connectors make up the EM3x module interface to the EM35x breakout board. In addition, two single-row, guide connectors on the EM35x breakout board assist with connecting the EM3x module to the breakout board. The board-to-board connector scheme allows access to all EM3x GPIO as well as nRESET and the JCLK signals. The connector is illustrated in Figure 3, while the connector dimensions are listed in Figure 4.

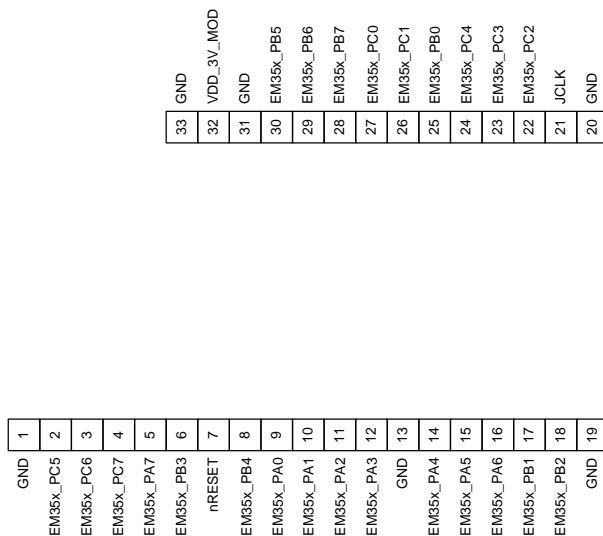


Figure 3. Board-to-board connector for the EM3x module (top view)

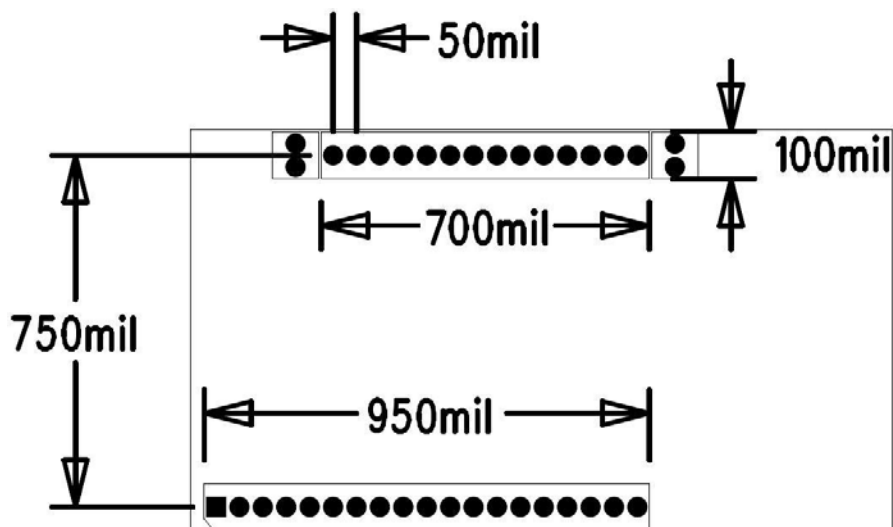


Figure 4. Board-to-Board Connector Dimensions for the EM3x Module (top view)

Table 8 describes the pinout and signal names on the connector.

For more information on the alternate functions of the GPIO connector, refer to the *EM35x Data Sheet*.

Table 8. Pinout and Signal Names of the Interface Connector

| Pin # | Signal name | Direction ¹ | Description |
|-------|-------------|------------------------|--|
| 1 | GND | Power | Ground Connection |
| 2 | PC5 | I/O | EM3x GPIO |
| 3 | PC6 | I/O | EM3x GPIO |
| 4 | PC7 | I/O | EM3x GPIO |
| 5 | PA7 | I/O | EM3x GPIO |
| 6 | PB3 | I/O | EM3x GPIO |
| 7 | nRESET | I/O | Active low chip reset (internal pull-up on EM3x) |
| 8 | PB4 | I/O | EM3x GPIO |
| 9 | PA0 | I/O | EM3x GPIO |
| 10 | PA1 | I/O | EM3x GPIO |
| 11 | PA2 | I/O | EM3x GPIO |
| 12 | PA3 | I/O | EM3x GPIO |
| 13 | GND | Power | Ground Connection |
| 14 | PA4 | I/O | EM3x GPIO |
| 15 | PA5 | I/O | EM3x GPIO |
| 16 | PA6 | I/O | EM3x GPIO (NC on EM346 module) |
| 17 | PB1 | I/O | EM3x GPIO |
| 18 | PB2 | I/O | EM3x GPIO |
| 19 | GND | Power | Ground connection |
| 20 | GND | Power | Ground connection |
| 21 | JCLK | Input | JTAG interface, serial clock |
| 22 | PC2 | I/O | EM3x GPIO |
| 23 | PC3 | I/O | EM3x GPIO |

TS8

| Pin # | Signal name | Direction ¹ | Description |
|-------|-------------|------------------------|----------------------------------|
| 24 | PC4 | I/O | EM3x GPIO |
| 25 | PB0 | I/O | EM3x GPIO |
| 26 | PC1 | I/O | EM3x GPIO |
| 27 | PC0 | I/O | EM3x GPIO |
| 28 | PB7 | I/O | EM3x GPIO (NC on EM346 module) |
| 29 | PB6 | I/O | EM3x GPIO (NC on EM346 module) |
| 30 | PB5 | I/O | EM3x GPIO (NC on EM346 module) |
| 31 | GND | Power | Ground connection |
| 32 | VDD | Power | 2.1 to 3.6 V Module Power Domain |
| 33 | GND | Power | Ground connection |

¹ with respect to the EM3x Module

CONTACT INFORMATION

Silicon Laboratories Inc.

400 West Cesar Chavez

Austin, TX 78701

Tel: 1+(512) 416-8500

Fax: 1+(512) 416-9669

Toll Free: 1+(877) 444-3032

For additional information please visit the Silicon Labs Technical Support page:

<http://www.silabs.com/support/Pages/default.aspx>

Patent Notice

Silicon Labs invests in research and development to help our customers differentiate in the market with innovative low-power, small size, analog-intensive mixed-signal solutions. Silicon Labs' extensive patent portfolio is a testament to our unique approach and world-class engineering team.

The information in this document is believed to be accurate in all respects at the time of publication but is subject to change without notice. Silicon Laboratories assumes no responsibility for errors and omissions, and disclaims responsibility for any consequences resulting from the use of information included herein. Additionally, Silicon Laboratories assumes no responsibility for the functioning of undescribed features or parameters. Silicon Laboratories reserves the right to make changes without further notice. Silicon Laboratories makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Silicon Laboratories assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. Silicon Laboratories products are not designed, intended, or authorized for use in applications intended to support or sustain life, or for any other application in which the failure of the Silicon Laboratories product could create a situation where personal injury or death may occur. Should Buyer purchase or use Silicon Laboratories products for any such unintended or unauthorized application, Buyer shall indemnify and hold Silicon Laboratories harmless against all claims and damages.

Silicon Laboratories, Silicon Labs, and Ember are registered trademarks of Silicon Laboratories Inc.

Other products or brandnames mentioned herein are trademarks or registered trademarks of their respective holders.